



Reliable Electronic Solutions

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Manufacturers Representatives
Corporate Distributor Product Managers
Americas Sales Team
Asia Sales Team
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Bourns® Integrated Passive & Active Device Product Line RoHS Compliance Product Update

Bourns is pleased to announce a lead free and RoHS update on the Integrated Passive & Active Device product families.

- The thin film on silicon networks using QSOP and NSOIC packages, within the product series 2CFA, 2CFB, 2CTE, 2DEA, 2DTF, 2DTG, 2QSP and 2NBS, are now RoHS compliant. Adding the LF suffix to the existing part number will provide 100 % tin solder on the lead frame terminations.

Example: 2QSP16-RJ2-103LF

- The thin film on silicon networks using Chip Scale Packages, within product series 2D and 2F, are now RoHS compliant. Adding the LF suffix to the existing part number will provide a Sn/Ag/Cu finish on solder bump terminations.

Example: 2FAE-C15RLF

Please direct any questions or concerns you may have to:

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Best regards,

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